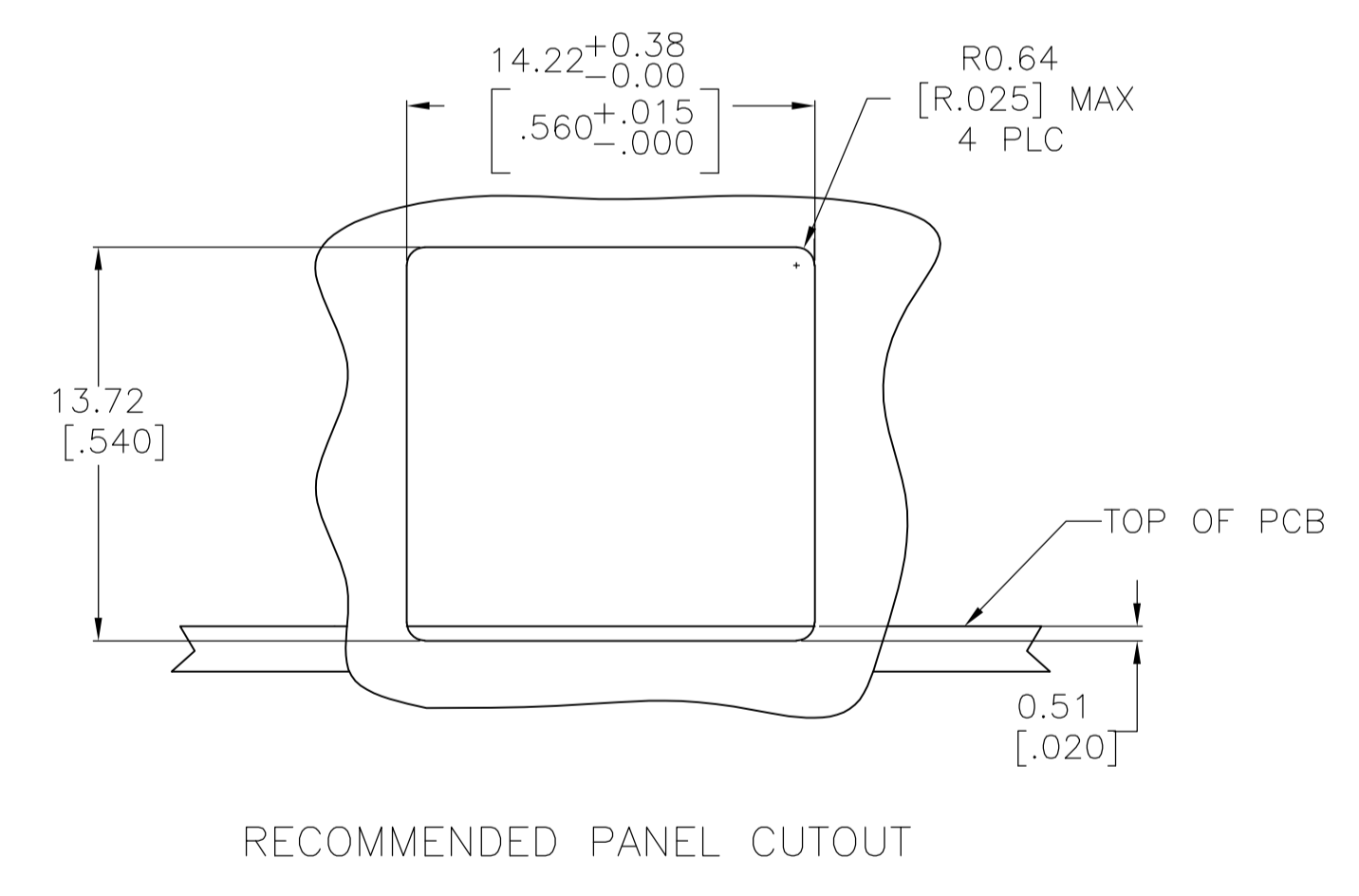
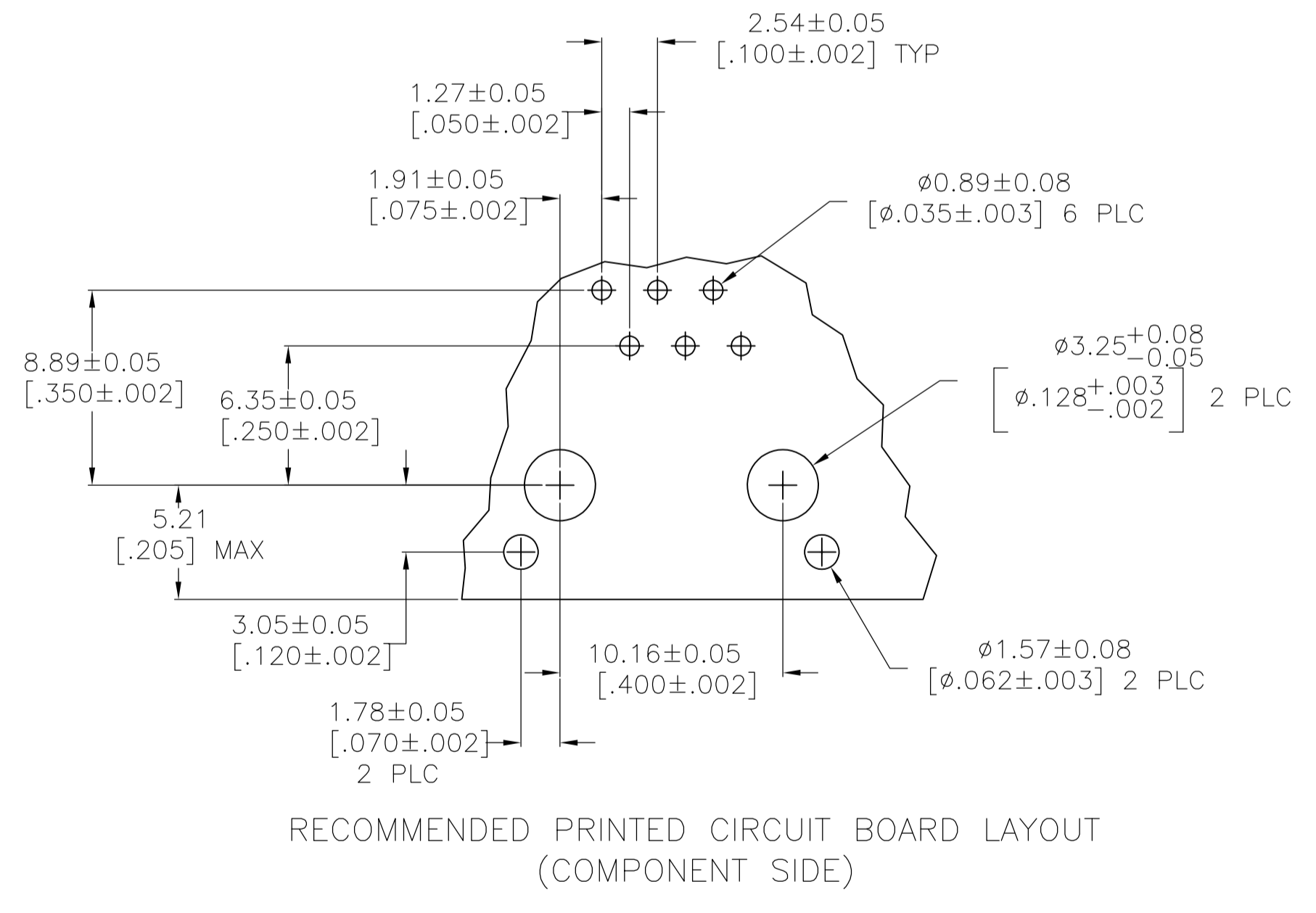


- MATERIAL: HOUSING - HTN NYLON, COLOR: BLACK
 TERMINAL - 0.36[.014] THICK PHOS-BRONZE PLATED WITH 1.27 μ m[.000050] MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81 μ m[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27 μ m[.000050] MINIMUM THICK NICKEL UNDERPLATE.
 SHIELD - 0.25[.010] THICK COPPER ALLOY, PLATED WITH 3.0 μ m[.000120] MINIMUM REFLOWED TIN
- △ JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
 - △ DIMENSION MEASURED ALONG FRONT EDGE OF MATING FACE



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT (COMPONENT SIDE)

RECOMMENDED PANEL CUTOUT

YES	5406435-2
NO	5406435-1
PANEL GROUND	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN J. ALCORTA - DOCK 5 09JUN2005		Tyco Electronics Corporation Harrisburg, PA 17105-3608	
DIMENSIONS: mm [INCHES]		CIR J. WESTMAN 09JUN2005		NAME S. FLICKINGER 09JUN2005	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		PRODUCT SPEC		MODULAR JACK ASSEMBLY, SHIELDED, 6 POSITION, LOW PROFILE, RIGHT ANGLE, PRINTED CIRCUIT BOARD GROUND WITH PANEL STOPS	
0 PLC ± -		APPLICATION SPEC		SIZE 108-1163	
1 PLC ± -		WEIGHT		SCALE 114-2048	
2 PLC ± -		CUSTOMER DRAWING		SHEET 1 OF 1	
3 PLC ± .005		SCALE 4:1		REV D	
4 PLC ± -		SCALE 4:1		REV D	
ANGLES ± -		SCALE 4:1		REV D	
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1		WEIGHT	
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1		WEIGHT	
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1		WEIGHT	
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1		WEIGHT	